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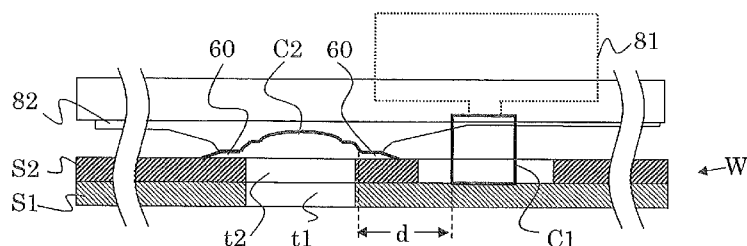


Fig. 18

(57) Abstract: The method for manufacturing a plurality of optical modules each comprising a first (C1) and a second (C2) optical component comprises the steps of a) providing a first substrate wafer (S1) on which a plurality of the first optical components (C1) is present on a top side of the first substrate wafer; b) providing a second substrate wafer (S2) having a material region which is a continuous laterally defined region in which material of the second substrate is present, wherein a plurality of the second optical components (C2) is present in said material region; c) achieving a lateral alignment of the first (S1) and second (S2) substrate wafers such that each of the first optical components (C1) is present in a laterally defined region not overlapping said material region; d) interconnecting the first and second substrate wafers in said lateral alignment such that the top side of the first substrate wafer faces a bottom side of the second substrate wafer with no further wafer in between. This way, first and second optical components may be placed particularly close to each other.

